

GAU 1754

TSMC 97-306

Serial Number 09/086,772



AMENDMENT AND RESPONSE TO OFFICE ACTION

6/10
P.Y.
9-3-99

TO: COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

FROM: George O. Saile (Reg. No. 19,572)
20 McIntosh Drive
Poughkeepsie, NY 12603

DATE: 1 August 1999

REF: APPLICANT : Jang et al. (hereinafter "applicant")
SERIAL NO. : 09/086,772
ART UNIT : 1754
FILING DATE : 29 May 1998
ATT'Y NO. : TSMC 97-306
EXAMINER : Cam Nguyen
TITLE : Hard Masking Method for Forming Patterned Oxygen
Containing Plasma Etchable Layer

Sir:

In response to an office action mailed on 1 July 1999, please consider the following amendments and remarks with respect to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class mail in an envelope addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 19 August 1999.

George O. Saile
Name

George O. Saile
Signature

Aug. 19, 1999
Date